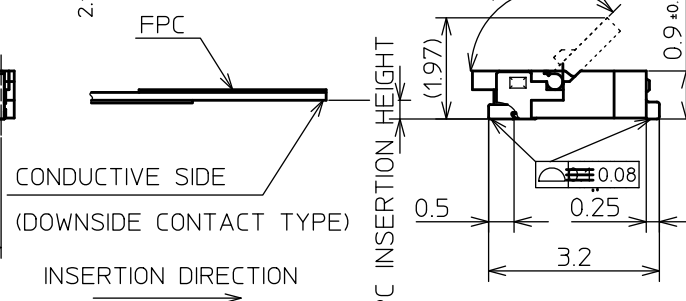
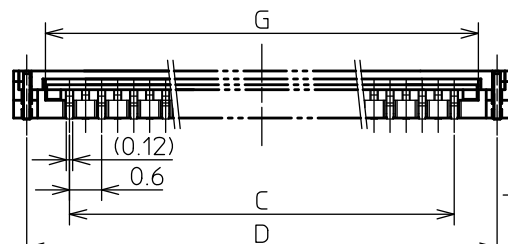
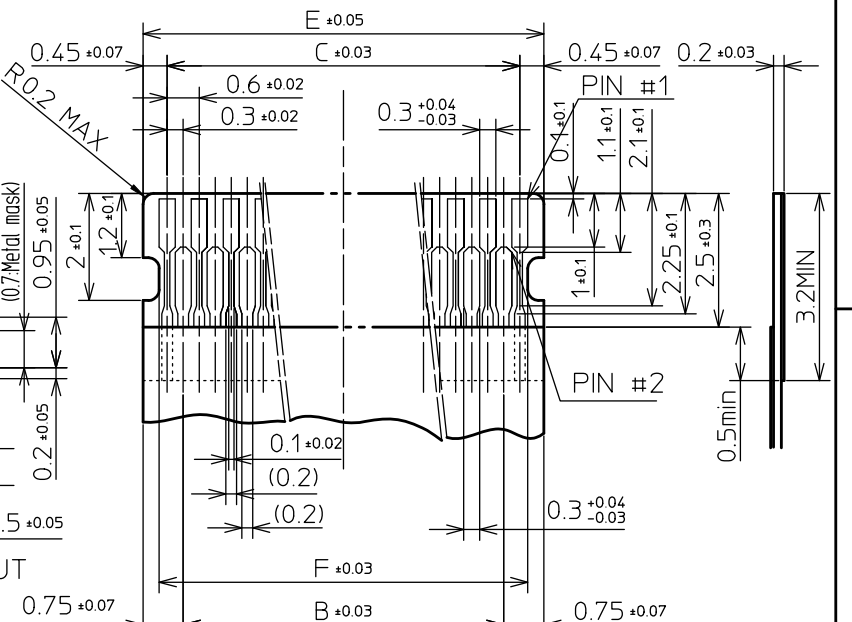
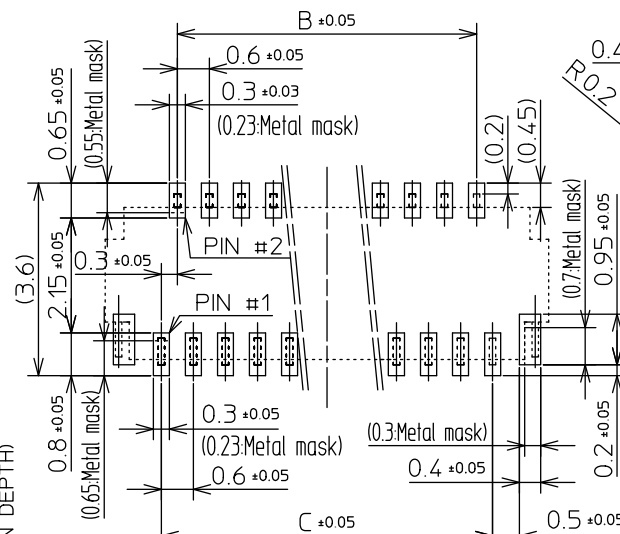


mat'l. code					surface ☒ ISO 1302 ☒ tolerance ☒ ISO 406 ☒ ISO 1101				product family 587F (YLL-D)		CODE JP	
lfr	description	ecn no	dr	date	tolerances unless otherwise specified				title		size	
S	REVISED	ELX-J-1461-1	T J	2013-03-05	angles	± 0.3			0.3mm PITCH FPC CONNECTOR			
R	REVISED	ELX-J-0924-5	T J	2012-08-31	linear				DOWN CONTACT TYPE ET PACKAGING			
P	REVISED	J11-0280	T J	2011-12-14	± 3							
N	REVISED	J10-0261	T J	2010-10-12					dwg no		sheet of	size
M	REVISED	J10-0185	T J	2010-07-06	eng	T.Jishihita			10061122		10F37	A2
L	REVISED	J10-0073	T J	2010-05-07	chr	H.Suzuki			2013-03-05			
K	REVISED	J08-0430	K O	2008-11-11	appd	N.Sasame			2013-03-05			
sheet	revision	S	N	G	A	B	C	C			Rev.	
index	sheet	1	2	3	4	5	6	7			S	

OBSOLETE

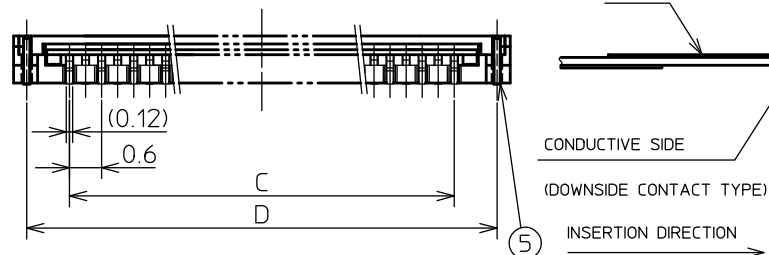


THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER
COUNTRY REGULATIONSAS DESCRIBED IN GS-22-008

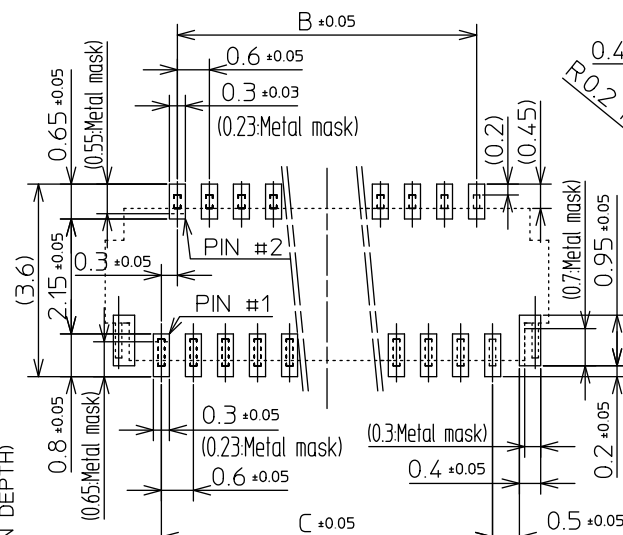
P/N	A	B	C	D	E	F	G	
40064122-43111LF	5.7	3.0	3.6	5.2	4.5	3.9	4.53	OBSOLETE
40064122-45111LF	6.3	3.6	4.2	5.8	5.1	4.5	5.13	OBSOLETE
40064122-47111LF	6.9	4.2	4.8	6.4	5.7	5.1	5.73	OBSOLETE
40064122-21111LF	8.1	5.4	6.0	7.6	6.9	6.3	6.93	OBSOLETE
40064122-23111LF	8.7	6.0	6.6	8.2	7.5	6.9	7.53	OBSOLETE
40064122-25111LF	9.3	6.6	7.2	8.8	8.1	7.5	8.13	OBSOLETE
40064122-33111LF	11.7	9.0	9.6	11.2	10.5	9.9	10.53	OBSOLETE
40064122-35111LF	12.3	9.6	10.2	11.8	11.1	10.5	11.13	OBSOLETE
40064122-39111LF	13.5	10.8	11.4	13.0	12.3	11.7	12.33	OBSOLETE
40064122-41111LF	14.1	11.4	12.0	13.6	12.9	12.3	12.93	OBSOLETE

[illegible]

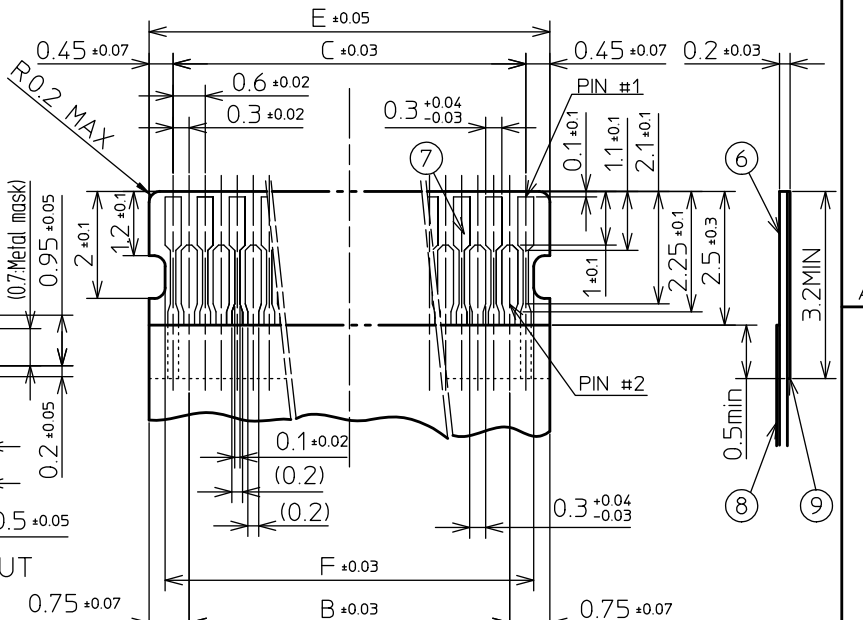
Printed: Mar 06, 2013



NOTE	nNO OF CONTACT
1.CO-PLANARITY:0.08mmMAX	
2.THICKNESS OF A METAL MASK:0.1mm	
3.FPC	
Adhesive method of supporting tape shall be heat crimping method and thermosetting adhesive material shall be used.	
4.PRODUCT	
Recommended PCB layout and FPC area the same as 10064555-**2110*LF(YLL-Upper contact type)	
5.OTHER	
This product meets European Union Directives and other country regulation as described in GS-22-008	



RECOMMENDED PC BOARD LAYOUT



RECOMMENDED FPC CONFIGURATION

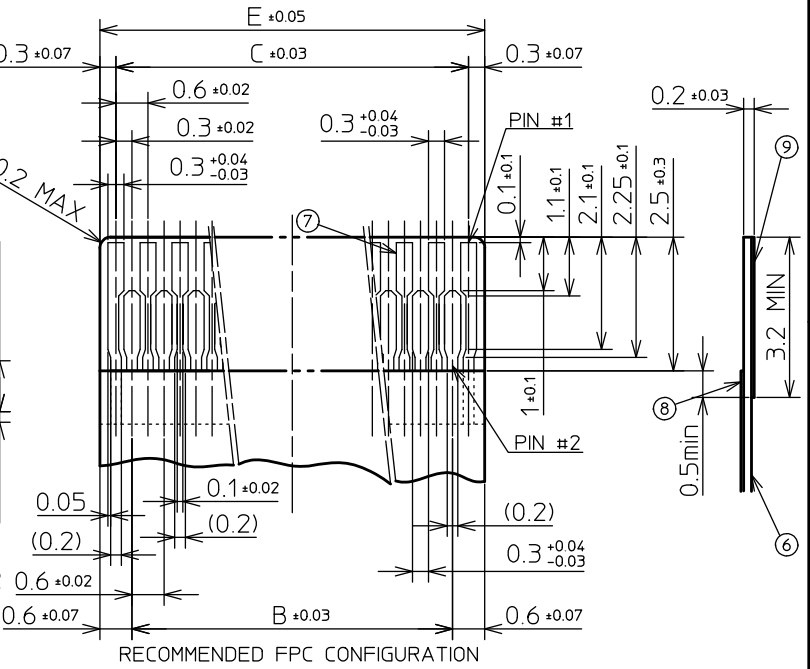
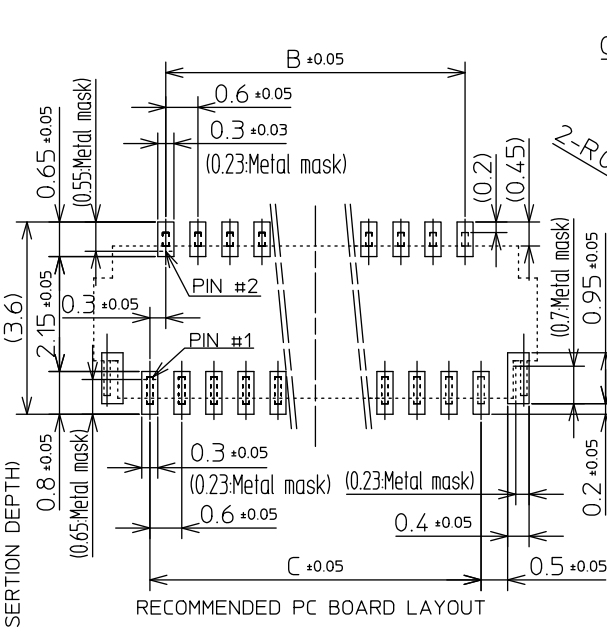
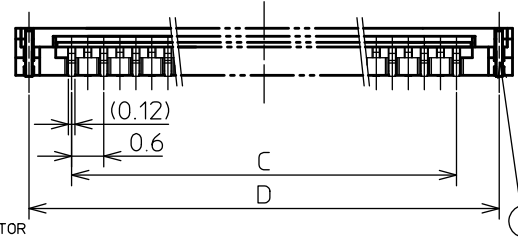
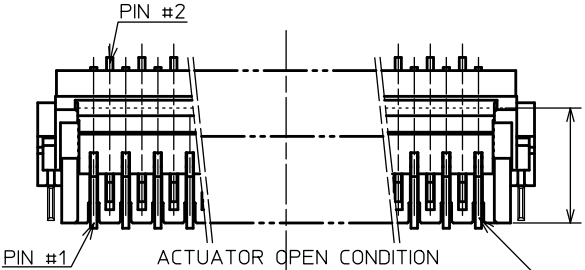
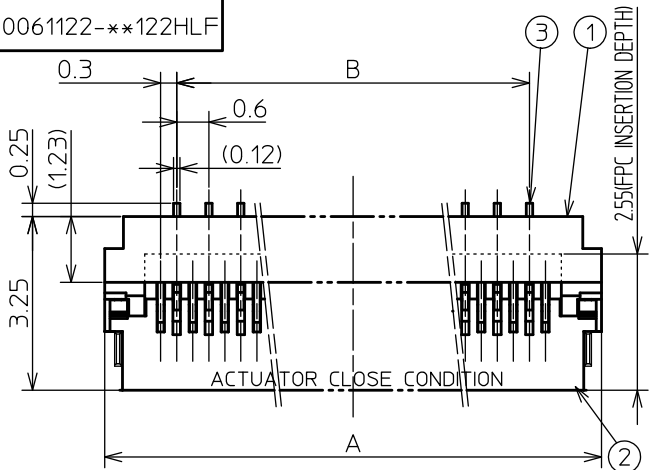
n: NO OF CONTACT

P/N	A	B	C	D	E	F
10061122-13112HLF	5.7	3.0	3.6	5.2	4.5	3.9
10061122-15112HLF	6.3	3.6	4.2	5.8	5.1	4.5
10061122-17112HLF	6.9	4.2	4.8	6.4	5.7	5.1
10061122-21112HLF	8.1	5.4	6.0	7.6	6.9	6.3
10061122-23112HLF	8.7	6.0	6.6	8.2	7.5	6.9
10061122-25112HLF	9.3	6.6	7.2	8.8	8.1	7.5

*For the corresponding position, please make an inquire to sales person in our company.

mat'l. code					surface ISO 1302 ✓		tolerance ISO 406 ISO 1101		projection 		product family 587F (YLL-D)			CODE JP	
lfr		description		ecn no		dr		date		tolerances unless otherwise specified					
A		Released		J10-0185		T.I.		2010-07-06		angles		linear		±0.2	
										±2'					
										dr		engr T.ISHISHITA		2010-07-06	
										chr		Y.Kameda		2010-07-06	
										appd		M.Kajiura		2010-07-06	
sheet index		revision sheet													

PRODUCT NO
10061122-**-122HLF



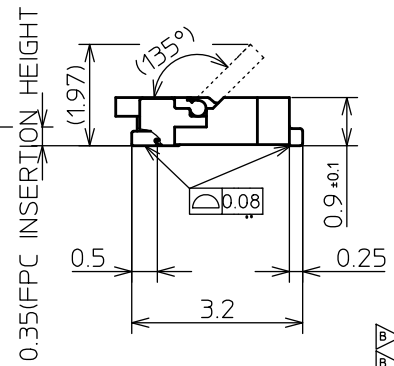
FPC			
PARTS NAME	MATERIAL	QTY	REMARKS
6 BASE FILM	POLYAMDE	1	
7 CONDUCTOR	COPPER FOIL	n	[PLATING] ALL OVER Ni 4~12 μm, Au 0.05~0.15 μm
8 OVERLAY	POLYAMIDE	1	
9 STIFFENER	POLYAMIDE	1	

n:NO OF CONTACT

PARTS NAME	MATERIAL	QTY	REMARKS
1 HOUSING	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0,COLOR:BLACK
2 ACTUATOR	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0,COLOR:NATURAL
3 CONTACT A	COPPER ALLOY	(n-1)/2	[PLATING] ALL OVER Ni(WITH Ni BARRIER) CONTACT AREA:Au SOLDER TAIL AREA:Au
4 CONTACT B	COPPER ALLOY	(n+1)/2	[PLATING] ALL OVER Ni,Sn
5 FIXING TAB	COPPER ALLOY	2	

n:NO OF CONTACT

NOTE
1.CO-PLANARITY:0.08mmMAX
2.THICKNESS OF A METAL MASK:0.1mm
3.FPC
Adhesive method of supporting tape shall be heat crimping method
and thermosetting adhesive material shall be used.
4.PRODUCT
Recommended PCB layout and FPC area the same as 10064555-**-2110*LF(YLL-Upper contact type)
5.OTHER
This product meets European Union Directives and other country reguation
as described in GS-22-008



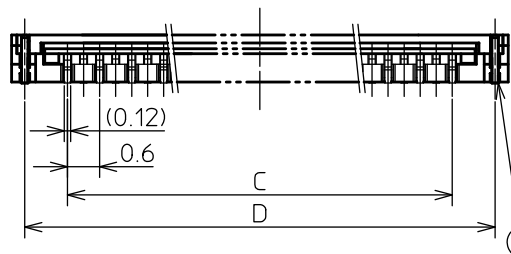
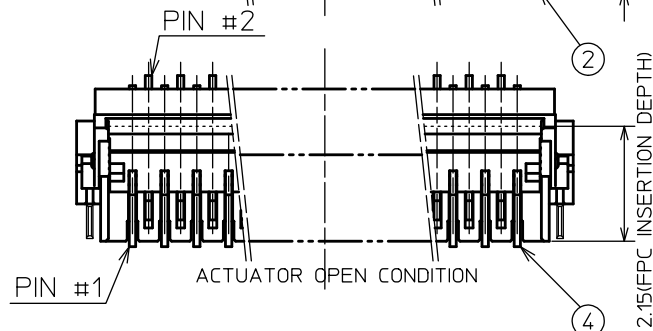
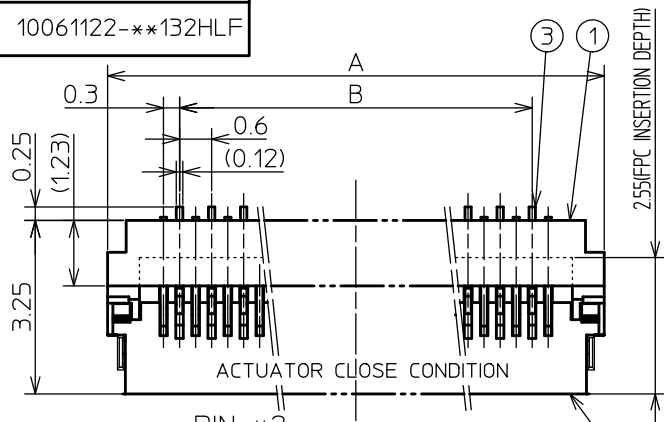
P/N	A	B	C	D	E
10061122-15122HLF	6.3	3.6	4.2	5.8	4.8
10061122-21122HLF	8.1	5.4	6.0	7.6	6.6
10061122-23122HLF	8.7	6.0	6.6	8.2	7.2
10061122-25122HLF	9.3	6.6	7.2	8.8	7.8

*For the corresponding position, please make an inquire to sales person in our company.

mat'l. code				surface		tolerance		projection		product family		CODE	
				ISO 1302		ISO 406 ISO 1101		MM		587F (YLL-D)		JP	
				tolerances unless otherwise specified		± 0.2				title			
				angles		linear		scale		0.3mm PITCH FPC CONNECTOR DOWN CONTACT TYPE			
				dr		T.JISHISHITA		2012-08-31		dwg no		sheet of	
				enr		H.Suzuki		2012-08-31		10061122		5of7	
				chr		M.Kajura		2012-08-31		type		Product Customer Drawing	
				appd									
				sheet		revision						Rev.	
				index								B	

PRODUCT NO.

10061122-**-132HLF



CONNECTOR

	PARTS NAME	MATERIAL	QTY	REMARKS
1	HOUSING	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0,COLOR:BLACK
2	ACTUATOR	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0,COLOR:NATURAL
3	CONTACT A	COPPER ALLOY	(n-1)/2	[PLATING] ALL OVER Ni(WITH Ni BARRIER) CONTACT AREA: Au
4	CONTACT B	COPPER ALLOY	(n+1)/2	SOLDER TAIL AREA: Au
5	FIXING TAB	COPPER ALLOY	2	[PLATING] ALL OVER Ni,Sn

NOTE

- 1.CO-PLANARITY:0.08mmMAX
2.THICKNESS OF A METAL MASK:0.1mm
3.FPC

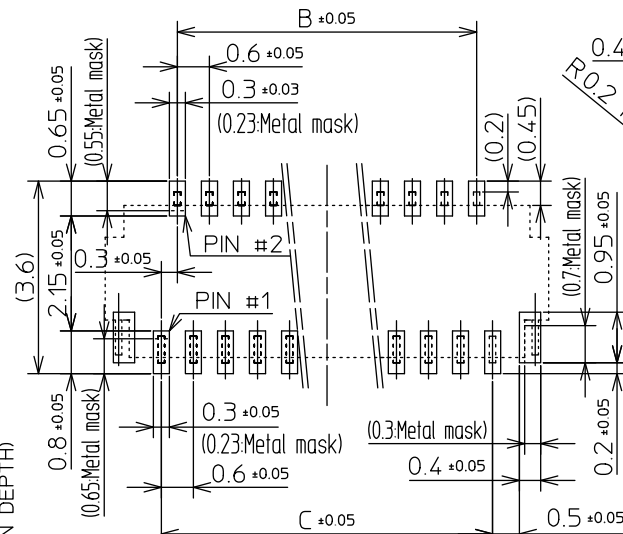
Adhesive method of supporting tape shall be heat crimping method and thermosetting adhesive material shall be used.

4.PRODUCT

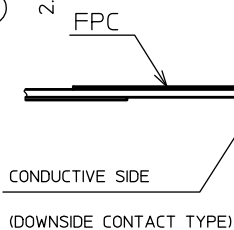
Recommended PCB layout and FPC area the same as 10064555-**-2110*LF(YLL-Upper contact type)

5.OTHER

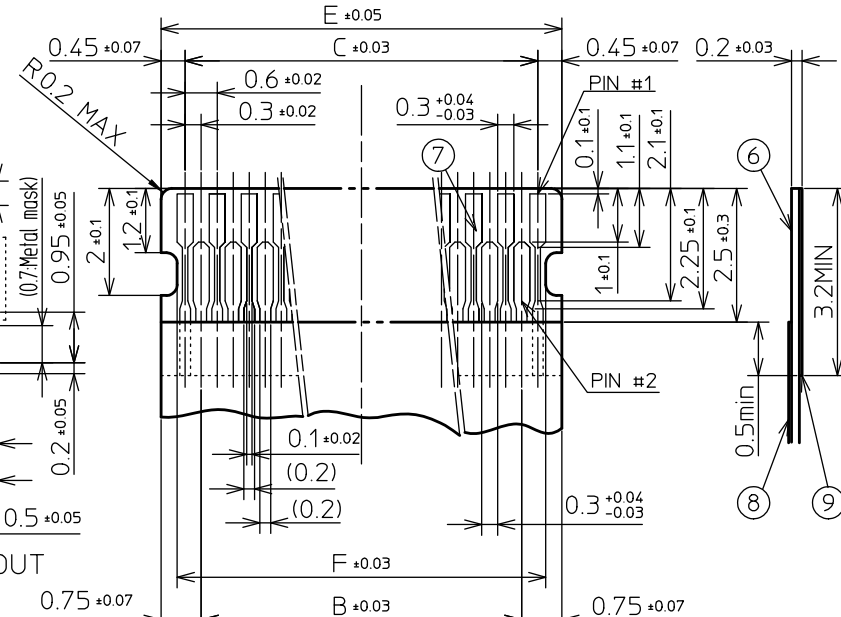
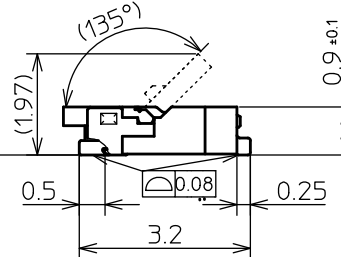
This product meets European Union Directives and other country regulation as described in GS-22-008



RECOMMENDED PC BOARD LAYOUT



0.35(FPC) INSERTION HEIGHT



RECOMMENDED FPC CONFIGURATION

FPC

	PARTS NAME	MATERIAL	QTY	REMARKS
6	BASE FILM	POLYAMIDE	1	
7	CONDUCTOR	COPPER FOIL	n	[PLATING] ALL OVER Ni 4~12μm, Au 0.05~0.15μm
8	OVERLAY	POLYAMIDE	1	
9	STIFFENER	POLYAMIDE	1	

n: NO OF CONTACT

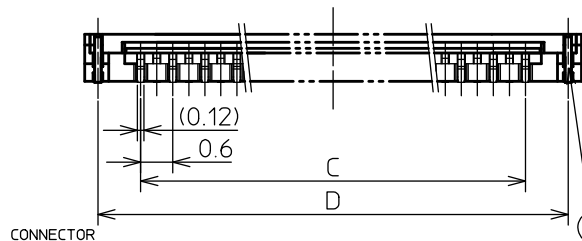
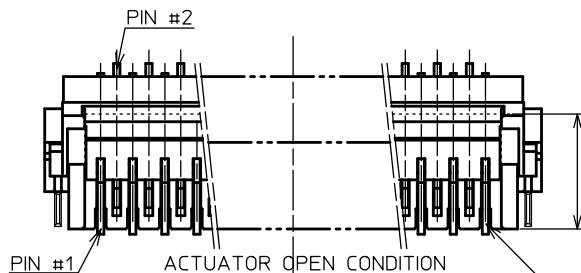
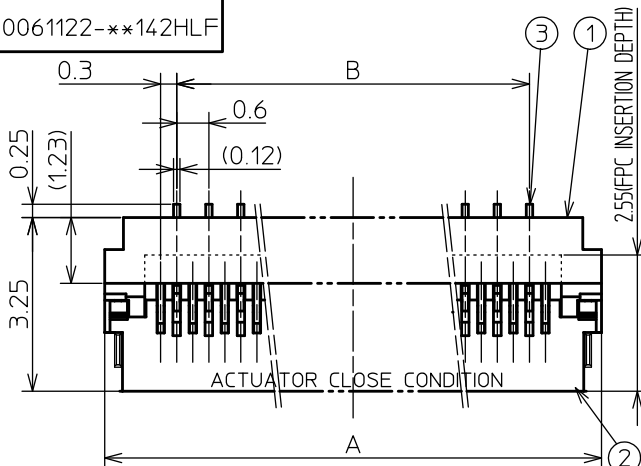
P/N	A	B	C	D	E	F
10061122-27132HLF	9.9	7.2	7.8	9.4	8.7	8.1
10061122-29132HLF	10.5	7.8	8.4	10.0	9.3	8.7
10061122-33132HLF	11.7	9.0	9.6	11.2	10.5	9.9
10061122-35132HLF	12.3	9.6	10.2	11.8	11.1	10.5
10061122-39132HLF	13.5	10.8	11.4	13.0	12.3	11.7
10061122-41132HLF	14.1	11.4	12.0	13.6	12.9	12.3
10061122-45132HLF	15.3	12.6	13.2	14.8	14.1	13.5

*For the corresponding position, please make an inquire to sales person in our company.

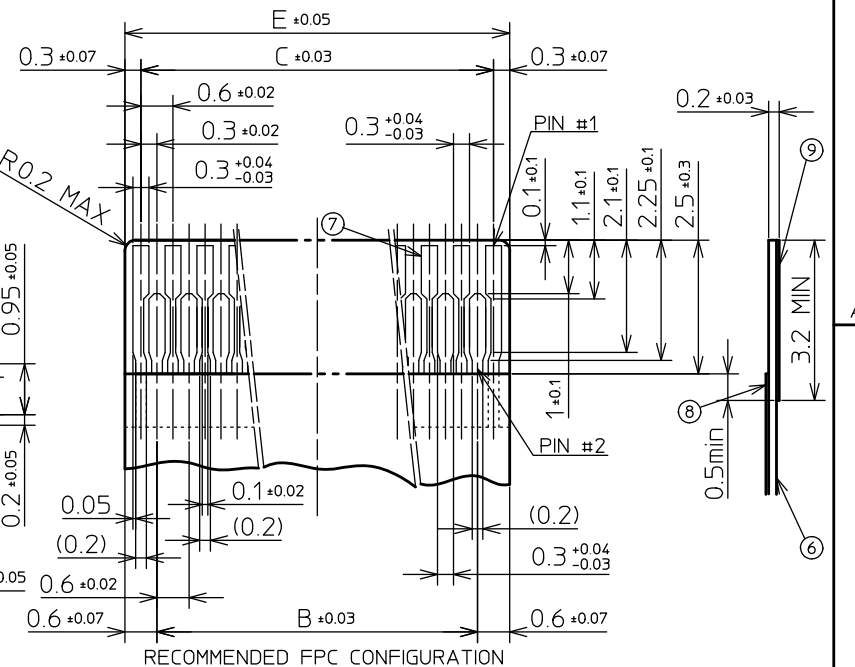
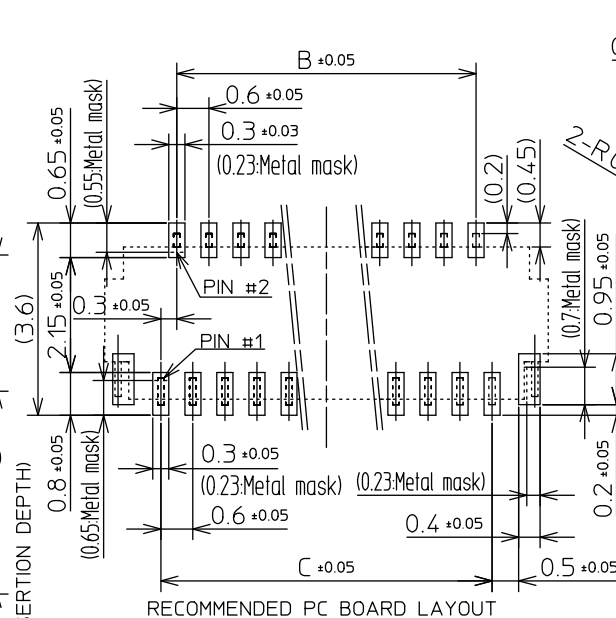
mat'l. code					surface ISO 1302 ✓		tolerance ISO 406 ISO 1101		projection 		product family 587F (YLL-D)				CODE JP				
lir		description		ecn no	dr	date	tolerances unless otherwise specified					title							
A		Released		J10-0185	T.I	2010-07-06	angles		linear	±0.2		0.3mm PITCH FPC CONNECTOR DOWN CONTACT TYPE							
B		Revised		J10-0268	T.I	2010-10-12													
C		Revised		ELX-J-012415-1	T.I	2012-08-31	±2'												
							dr	T.SHISHITA		2012-08-31				dwg no		sheet of		size	
							enrg	H Suzuki		2012-08-31				10061122		6of7		A3	
							chr	MKajiura		2012-08-31									
							appd							type		Product Customer		Drawing	
sheet index		revision sheet																Rev.	

PRODUCT NO

10061122-**-142HLF



CONDUCTIVE SIDE
(DOWNSIDE CONTACT TYPE)
INSERTION DIRECTION



FPC

PARTS NAME	MATERIAL	QTY	REMARKS
6 BASE FILM	POLYAMDE	1	
7 CONDUCTOR	COPPER FOIL	n	[PLATING] ALL OVER Ni 4~12μm, Au 0.05~0.15μm
8 OVERLAY	POLYAMIDE	1	
9 STIFFENER	POLYAMIDE	1	

n:NO OF CONTACT

P/N	A	B	C	D	E
10061122-33142HLF	11.7	9.0	9.6	11.2	10.2
10061122-39142HLF	13.5	10.8	11.4	13.0	12.0
10061122-41142HLF	14.1	11.4	12.0	13.6	12.6
10061122-43142HLF	14.7	12.0	12.6	14.2	13.2
10061122-45142HLF	15.3	12.6	13.2	14.8	13.8
10061122-51142HLF	17.1	14.4	15.0	16.6	15.6

*For the corresponding position, please make an inquire to sales person in our company.

PARTS NAME	MATERIAL	QTY	REMARKS
1 HOUSING	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0,COLOR:BLACK
2 ACTUATOR	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0,COLOR:NATURAL
3 CONTACT A	COPPER ALLOY	(n-1)/2	[PLATING] ALL OVER Ni(WITH Ni BARRIER) CONTACT AREA:Au SOLDER TAIL AREA:Au
4 CONTACT B	COPPER ALLOY	(n+1)/2	[PLATING] ALL OVER Ni:Sn
5 FIXING TAB	COPPER ALLOY	2	[PLATING] ALL OVER Ni:Sn

n:NO OF CONTACT

NOTE
1.CO-PLANARITY:0.08mmMAX
2.THICKNESS OF A METAL MASK:0.1mm
3.FPC

Adhesive method of supporting tape shall be heat crimping method
and thermosetting adhesive material shall be used.

4.PRODUCT

Recommended PCB layout and FPC area the same as 10064555-**-2110*LF(YLL-Upper contact type)
5.OTHER

This product meets European Union Directives and other country regulation
as described in GS-22-008

mat'l. code					surface		tolerance		projection		product family				CODE		
					ISO 1302		ISO 406 ISO 1101				587F (YLL-D)				JP		
lfr		description		ecn no.	dr	date		tolerances unless otherwise specified				title					
A		Released		J10-0185	T.I	2010-07-06		angles		linear	± 0.2				0.3mm PITCH FPC CONNECTOR DOWN CONTACT TYPE		
B		Revised		ELX-J-01245-1	T.I	2012-08-31											
C		Revised		ELX-J-14161-1	T.I	2013-03-05		± 2°									
					dr		T.ISHISHITA		2013-03-05				dwg no		sheet of		size
					engr								10061122		7of7		A3
					chr		H.Suzuki		2013-03-05								
					appd		N.Sasame		2013-03-05				type		Product Customer		Drawing
sheet index		revision sheet															Rev. C

Mouser Electronics

Authorized Distributor

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FCI:

[10061122-331210ELF](#) [10061122-151210ELF](#) [10061122-251110ELF](#)